

[SOLDER PADS FOR IMPROVING RELIABILITY OF A PACKAGE]

Abstract of Disclosure

Solder pads for improving reliability of a semiconductor package are provided. The package includes a substrate and/or a chip. The solder pad includes a plurality of first solder pads located on a surface of the substrate and/or the chip, and at least a second solder pad located on a predetermined region of the surface of the substrate and/or the chip. Each of the first solder pads has a first diameter. The second solder pad has a second diameter greater than the first diameter so as to sustain a stronger thermal stress on the substrate and/or the chip.

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Figures

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